

规格书编号

SPEC NO:

产品规格书 SPECIFICATION

CUSTOMER 客 户:							
PRODUCT 产品:	SAW RESONATOR						
MODEL NO 型 号:	HDR318M-D	11					
PREPARED 编 制:	CHECKED 审 相	亥:					
APPROVED 批 准:	DATE 日 其	用: 2006-5-11					
客户确认 CUSTOMER RECEIVED:							
审核 CHECKED	批准 APPROVED	日期 DATE					

无锡市好达电子有限公司 Shoulder Electronics Limited



更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. SCOPE

This specification shall cover the characteristics of 1-port SAW resonator with 318M used for remote-control security.

2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V		
AC Voltage Vpp	10V50Hz/60Hz		
Operation temperature	-40°C to +85°C		
Storage temperature	-45°C to +85°C		
RF Power Dissipation	0dBm		

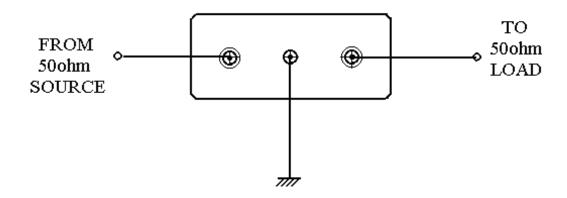
2.2 Electronic Characteristics

Item		Unites	Minimum	Typical	Maximum	
Center Frequency		MHz	317.925	318.000	318.075	
Insertion Loss		dB		1.6	2.2	
Quality Factor		Unload Q		8000	12800	
		50Ω Loaded Q		1000	1500	
Temperature	Turnover Temperature Freq.temp.Coefficient		$^{\circ}$	10	25	40
Stability			ppm/℃		0.032	
Frequency Aging		ppm/yr		<±10		
DC. Insulation Resistance		ΜΩ	1.0			
RF	Motional Resistance R1		Ω		20	26
Equivalent	Motional Inductance L1		μН		160.55	
RLC Model	odel Motional Capacitance C1		fF		1.56	
Transducer Static Capacitance C0		pF		2.0		

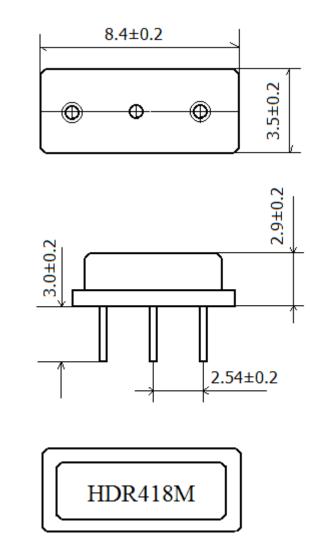




3. TEST CIRCUIT



4. DIMENSION



5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling



SAW RESONATOR

HDR318M-D11

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+25^{\circ}\text{C}$ for 5 Minutes and a higher temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2.2.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260° C $\pm 5^{\circ}$ C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

5-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the resonator shall fulfill the specifications in 2.2.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The resonator shall fulfill the specifications in 2.2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.